

FDSS2407

N-Channel Dual MOSFET

62V, 3.3A, 132mΩ

Features

- 62V, 132mΩ, 5V Logic Level Gate Dual MOSFET in SO-8
- 5V Logic Level feedback signal of the drain to source voltage. Multiple devices can be wired "OR'd" to a single monitoring circuit input.
- Gate Drive Disable Input. Multiple devices controllable by a single disable transistor.
- Qualified to AEC Q101

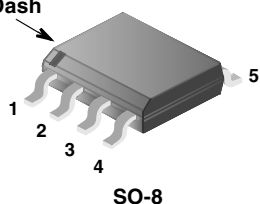
Applications

- Automotive Injector Driver
- Solenoid Driver

General Description

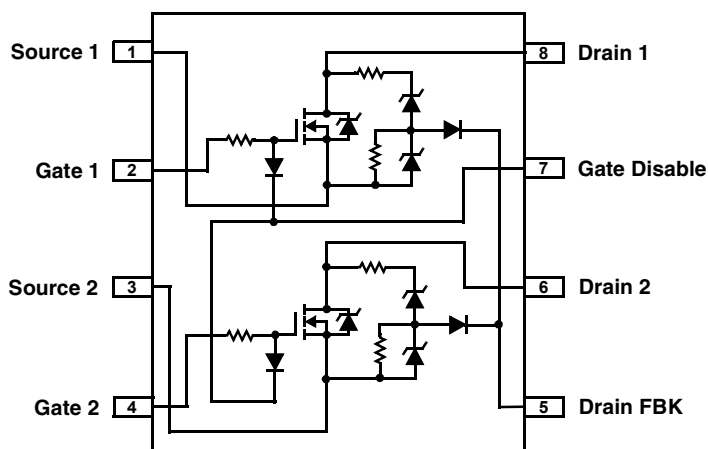
This dual N-Channel MOSFET provides added functions as compared to a conventional Power MOSFET. These are: 1. A drain to source voltage feedback signal and 2. A gate drive disable control function that previously required external discrete circuitry. Including these functions within the MOSFET saves printed circuit board space. The drain to source voltage feedback function provides a 5V level output whenever the drain to source voltage is above 62V. This can monitor the time an inductive load takes to dissipate its stored energy. Multiple feedback signals can be wired "OR'd" together to a single input of the monitoring circuit. The gate disable function allows the device to be turned off independent of the drive signal on the gate. This function permits a second control circuit the ability to deactivate the load if necessary. It can also be wired "OR'd" allowing multiple devices to be controlled by a single open collector / drain control transistor.

Branding Dash



Pin 5 - Drain Feedback Output
Pin 7 - Gate Drive Disable Input

Internal Diagram



MOSFET Maximum Ratings $T_A=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain to Source Voltage	62	V
V_{GS}	Gate to Source Voltage	± 20	V
I_{D}	Drain Current		
	Continuous ($T_A = 25^{\circ}\text{C}$, $V_{\text{GS}} = 10\text{V}$, $R_{\theta\text{JA}} = 55^{\circ}\text{C/W}$)	3.3	A
	Continuous ($T_A = 25^{\circ}\text{C}$, $V_{\text{GS}} = 5\text{V}$, $R_{\theta\text{JA}} = 55^{\circ}\text{C/W}$)	3.0	A
	Pulsed	Figure 4	A
E_{AS}	Single Pulse Avalanche Energy (Note 1)	140	mJ
P_{D}	Power dissipation	2.27	W
	Derate above 25°C	18	mW/ $^{\circ}\text{C}$
$T_{\text{J}}, T_{\text{STG}}$	Operating and Storage Temperature	-55 to 150	$^{\circ}\text{C}$

Thermal Characteristics

$R_{\theta\text{JA}}$	Pad Area = 0.50 in^2 (323 mm^2) (Note 2)	55	$^{\circ}\text{C/W}$
$R_{\theta\text{JA}}$	Pad Area = 0.027 in^2 (17.4 mm^2) (Note 3)	180	$^{\circ}\text{C/W}$
$R_{\theta\text{JA}}$	Pad Area = 0.006 in^2 (3.87 mm^2) (Note 4)	200	$^{\circ}\text{C/W}$

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
2407	FDSS2407	SO-8	330 mm	12 mm	2500

Electrical Characteristics $T_A = 25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

B_{VDS}	Drain to Source Breakdown Voltage	$I_{\text{D}} = 5\text{mA}$, $V_{\text{GS}} = 0\text{V}$	62	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 15\text{V}$, $V_{\text{GS}} = 0\text{V}$	-	-	1	μA
		$V_{\text{DS}} = 15\text{V}$, $V_{\text{GS}} = 0\text{V}$, $T_A = 150^{\circ}\text{C}$	-	-	250	
I_{GSS}	Gate to Source Leakage Current	$V_{\text{GS}} = \pm 20\text{V}$	-	-	± 100	nA

On Characteristics

$V_{\text{GS(TH)}}$	Gate to Source Threshold Voltage	$V_{\text{GS}} = V_{\text{DS}}$, $I_{\text{D}} = 250\mu\text{A}$	1	-	3	V
$r_{\text{DS(ON)}}$	Drain to Source On Resistance	$I_{\text{D}} = 3.3\text{A}$, $V_{\text{GS}} = 10\text{V}$	-	0.099	0.110	Ω
		$I_{\text{D}} = 3.0\text{A}$, $V_{\text{GS}} = 5\text{V}$	-	0.115	0.132	

Dynamic Characteristics

C _{ISS}	Input Capacitance	V _{DS} = 15V, V _{GS} = 0V, f = 75kHz		-	300	-	pF
C _{OSS}	Output Capacitance			-	140	-	pF
C _{RSS}	Reverse Transfer Capacitance			-	16	-	pF
R _G	Gate Resistance			-	8500	-	Ω
Q _{g(TOT)}	Total Gate Charge at 5V	V _{GS} = 0V to 5V	V _{DD} = 30V I _D = 3.3A I _g = 1.0mA	-	3.3	4.3	nC
Q _{g(TH)}	Threshold Gate Charge	V _{GS} = 0V to 1V		-	0.4	0.5	nC
Q _{gs}	Gate to Source Gate Charge			-	1.2	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau			-	0.8	-	nC
Q _{gd}	Gate to Drain “Miller” Charge			-	2.0	-	nC

Switching Characteristics ($V_{GS} = 10V$)

t_{ON}	Turn-On Time	$V_{DD} = 30V, I_D = 3.3A$ $V_{GS} = 10V, R_{GS} = 47\Omega$	-	-	2700	ns
$t_{d(ON)}$	Turn-On Delay Time		-	630	-	ns
t_r	Rise Time		-	1200	-	ns
$t_{d(OFF)}$	Turn-Off Delay Time		-	8700	-	ns
t_f	Fall Time		-	3500	-	ns
t_{OFF}	Turn-Off Time		-	-	18500	ns

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Voltage	$I_{SD} = 3.3A$	-	-	1.25	V
		$I_{SD} = 1.7A$	-	-	1.0	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 3.3A, dI_{SD}/dt = 100A/\mu s$	-	-	45	ns
Q_{RR}	Reverse Recovered Charge	$I_{SD} = 3.3A, dI_{SD}/dt = 100A/\mu s$	-	-	60	nC

Drain Feedback Characteristics

$V_{FBK(Low)}$	Feedback to Source Voltage	$V_{DS} = 35V, R_{FBK-SOURCE} = 51K\Omega$	-	1	1.5	V
$V_{FBK(High)}$	Feedback to Source Voltage	$V_{DS} = 62V, R_{FBK-SOURCE} = 51K\Omega$	3.5	4.4	-	V

Gate Drive Disable Characteristics

$V_{DIS(High)}$	Gate Drive Disable Input Voltage, Gate Enabled	$V_{GS} = 5V, I_D = 3.0A, T_J = 25^\circ C$	3	-	-	V
$V_{DIS(Low)}$	Gate Drive Disable Input Voltage, Gate Disabled	$V_{GS} = V_{DS} = 10V, I_D \leq 250\mu A, T_J = 150^\circ C$	-	-	0.4	V

Notes:

1. Starting $T_J = 25^\circ C, L = 42mH, I_{AS} = 2.6A, V_{DD} = 62V, V_{GS} = 10V$.
2. $55^\circ C/W$ measured using FR-4 board with $0.50 in^2$ ($323 mm^2$) copper pad at 1 second.
3. $180^\circ C/W$ measured using FR-4 board with $0.027 in^2$ ($17.4 mm^2$) copper pad at 1000 seconds.
4. $200^\circ C/W$ measured using FR-4 board with $0.006 in^2$ ($3.87 mm^2$) copper pad at 1000 seconds.

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: <http://www.aecouncil.com/>

All Fairchild Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

Typical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

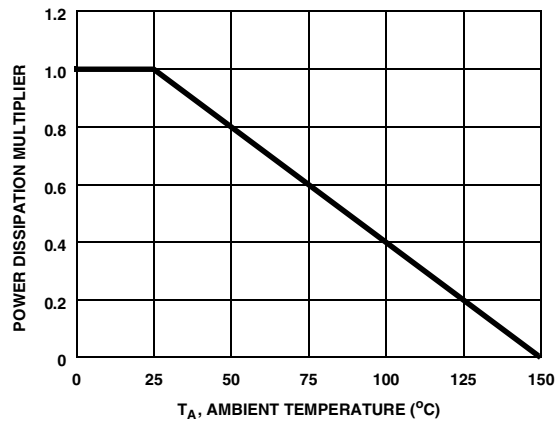


Figure 1. Normalized Power Dissipation vs Ambient Temperature

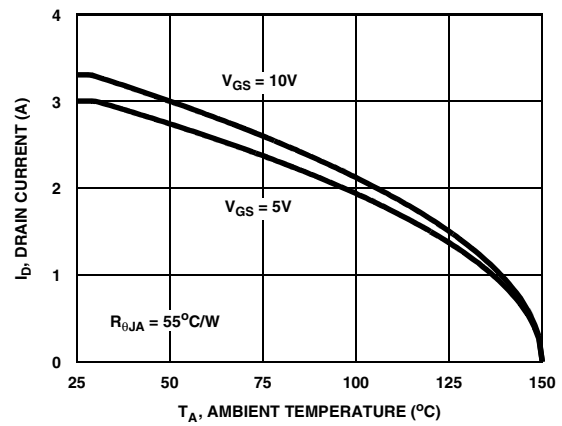


Figure 2. Maximum Continuous Drain Current vs Ambient Temperature

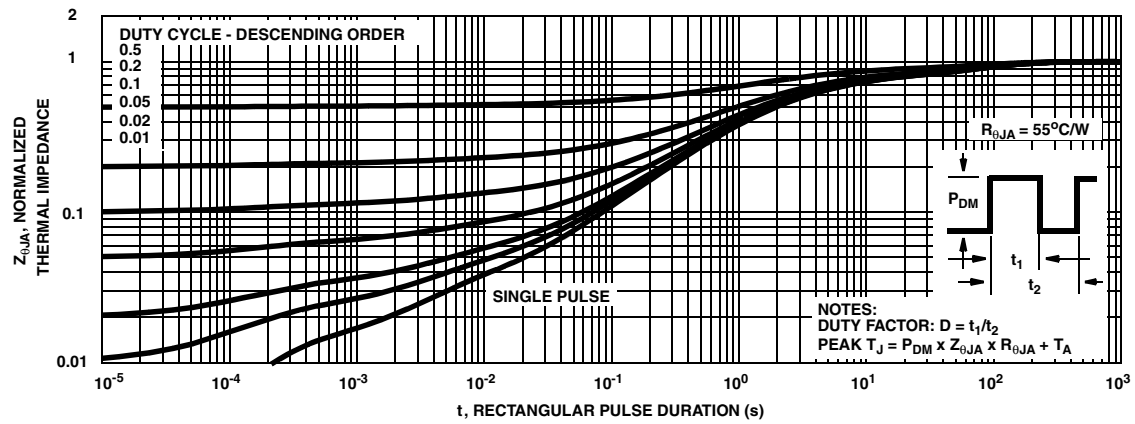


Figure 3. Normalized Maximum Transient Thermal Impedance

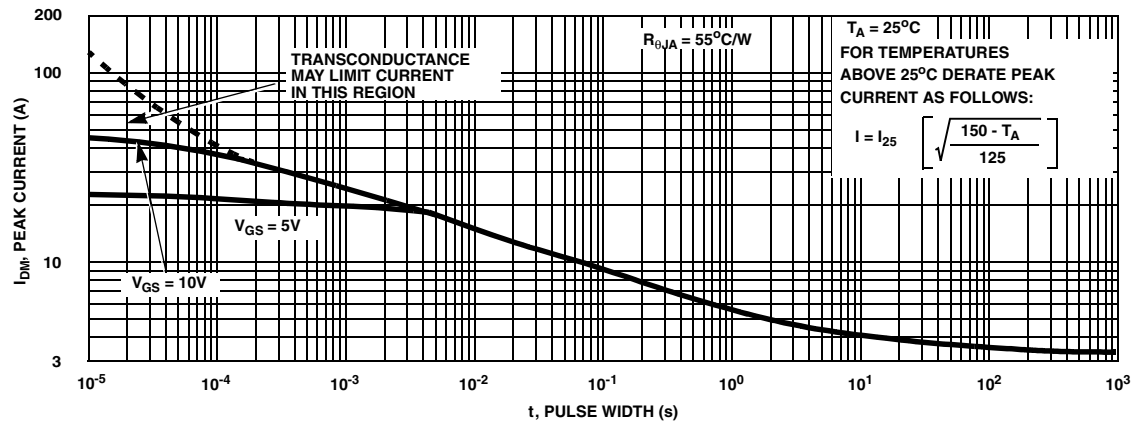


Figure 4. Peak Current Capability

Typical Characteristics (Continued) $T_A = 25^\circ\text{C}$ unless otherwise noted

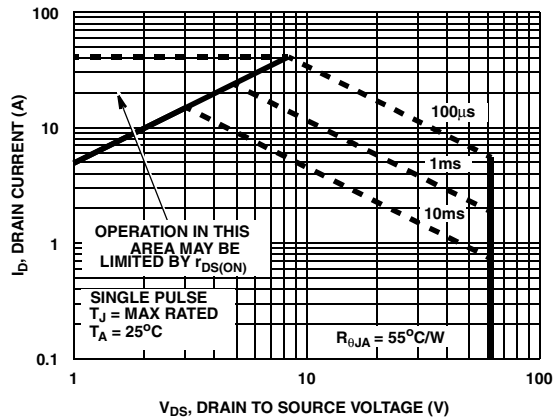
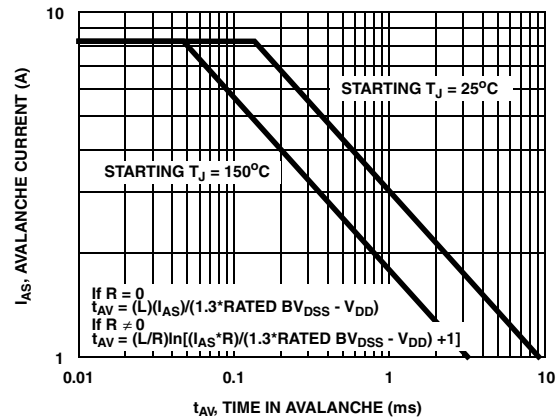


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515
Figure 6. Unclamped Inductive Switching Capability

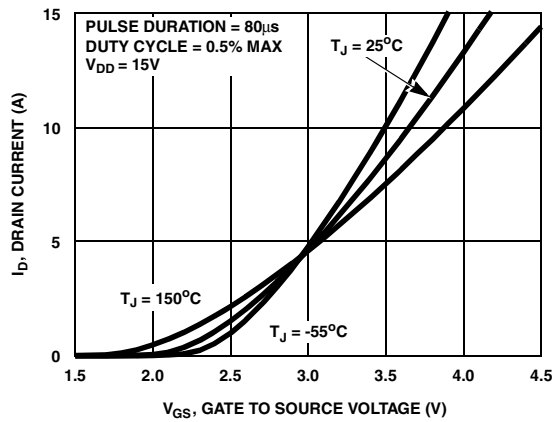


Figure 7. Transfer Characteristics

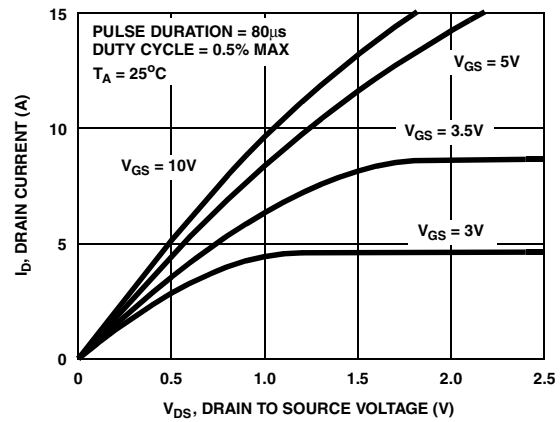


Figure 8. Saturation Characteristics

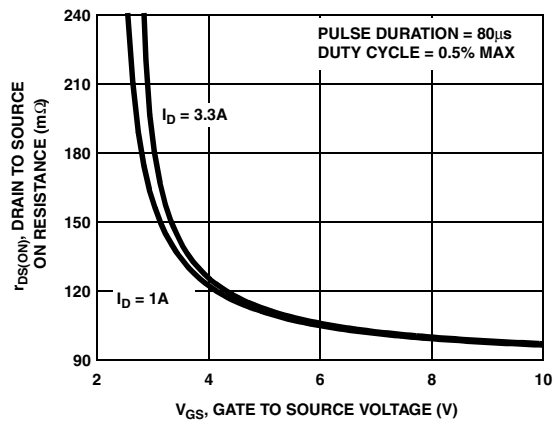


Figure 9. Drain to Source On Resistance vs. Gate Voltage and Drain Current

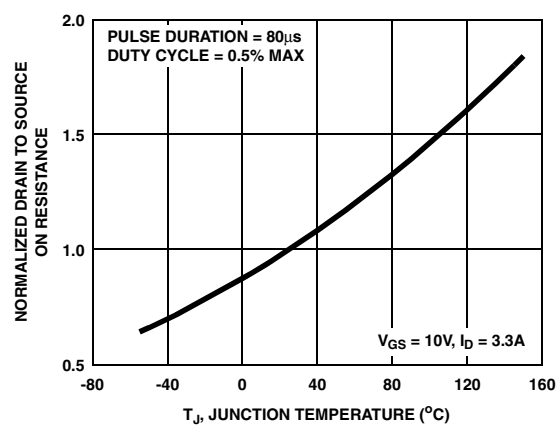


Figure 10. Normalized Drain to Source On Resistance vs. Junction Temperature

Typical Characteristics (Continued) $T_A = 25^\circ\text{C}$ unless otherwise noted

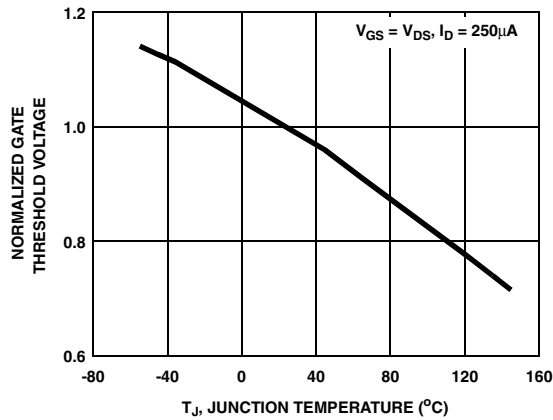


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

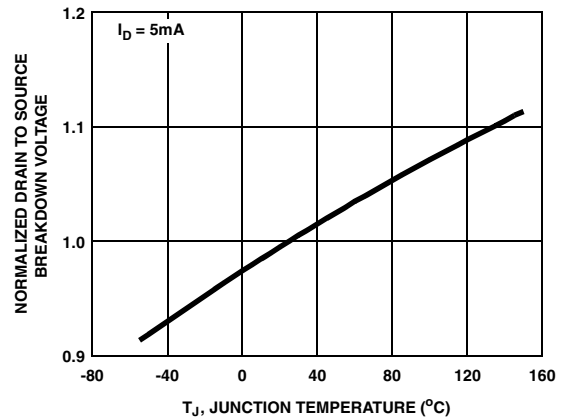


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

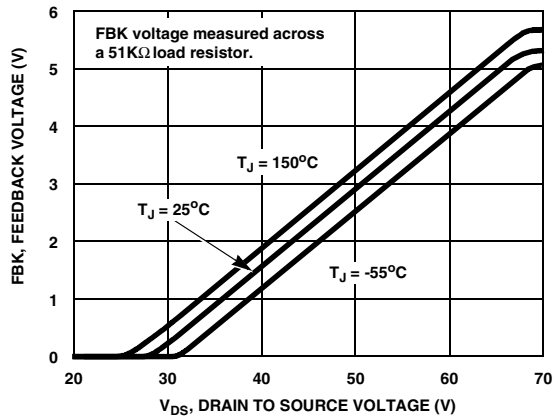


Figure 13. Feedback Voltage vs Drain to Source Voltage

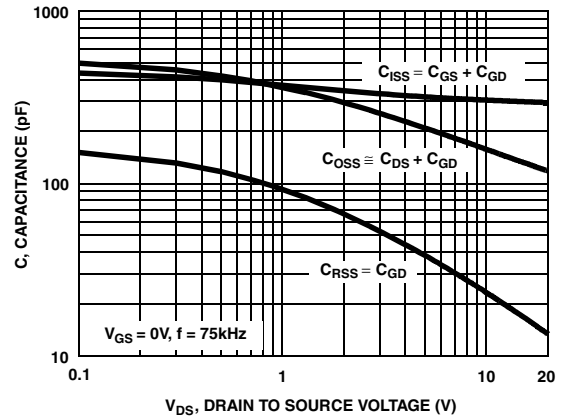


Figure 14. Capacitance vs Drain to Source Voltage

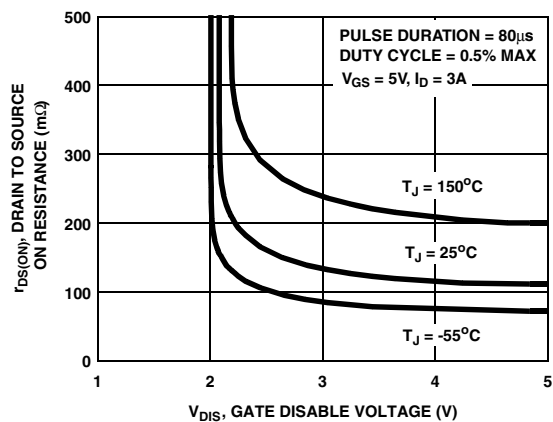


Figure 15. Drain to Source On Resistance vs Gate Disable Voltage

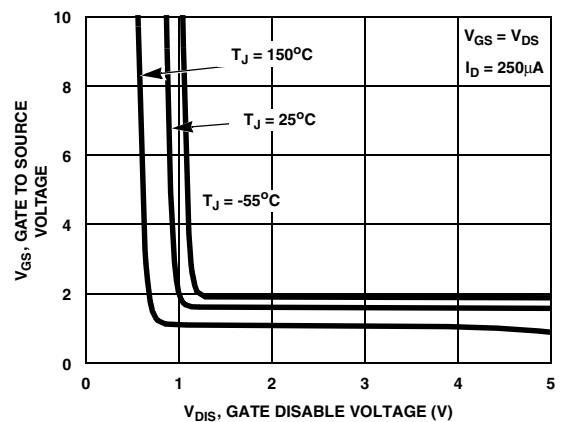


Figure 16. Gate to Source Voltage vs Gate Disable Voltage

Typical Characteristics (Continued) $T_A = 25^\circ\text{C}$ unless otherwise noted

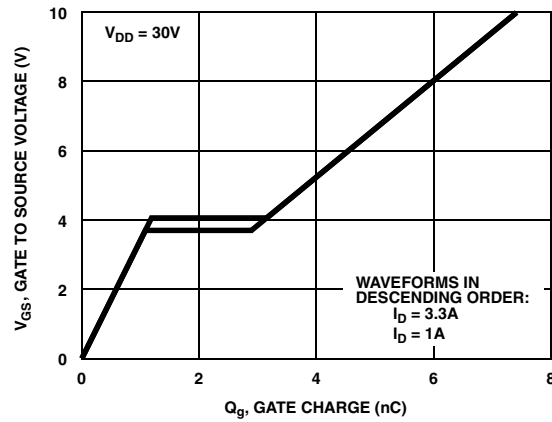


Figure 17. Gate Charge Waveforms for Constant Gate Currents

Test Circuits and Waveforms

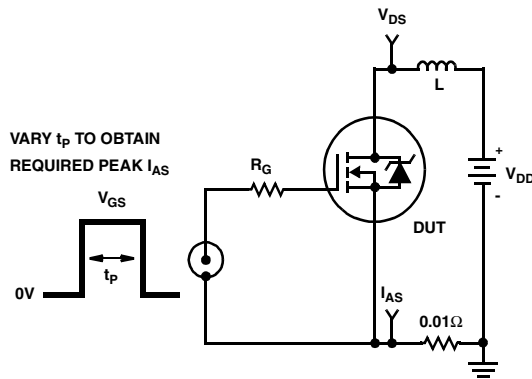


Figure 18. Unclamped Energy Test Circuit

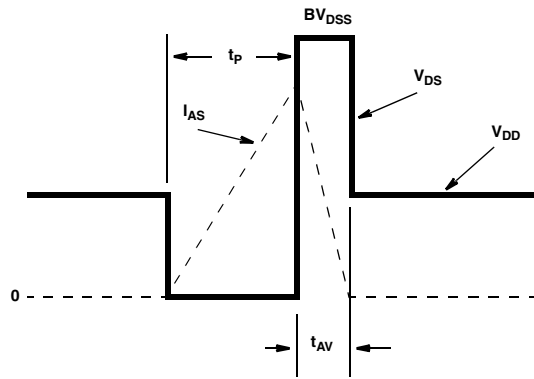


Figure 19. Unclamped Energy Waveforms

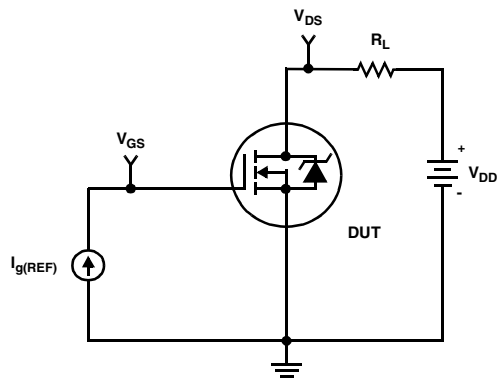


Figure 20. Gate Charge Test Circuit

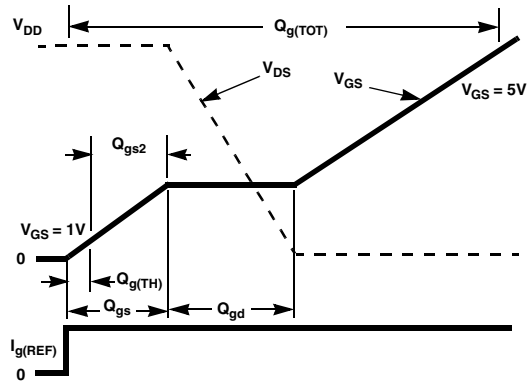


Figure 21. Gate Charge Waveforms

Test Circuits and Waveforms (Continued)

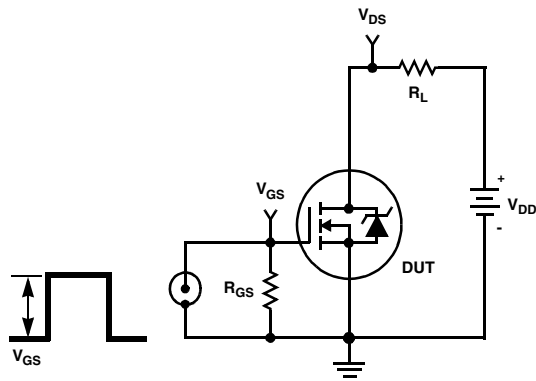


Figure 22. Switching Time Test Circuit

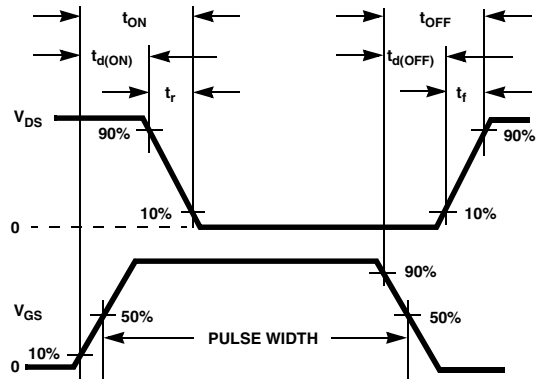


Figure 23. Switching Time Waveforms

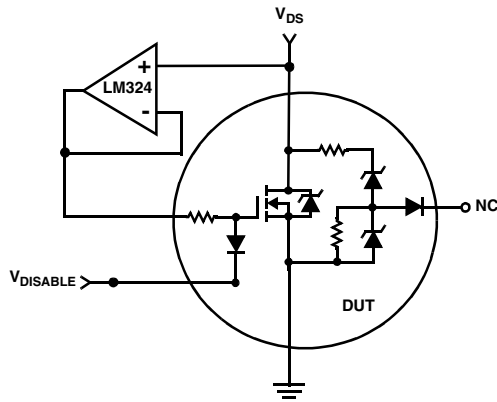


Figure 24. Gate to Source Voltage vs Gate Disable Voltage

Thermal Resistance vs. Mounting Pad Area

The maximum rated junction temperature, T_{JM} , and the thermal resistance of the heat dissipating path determines the maximum allowable device power dissipation, P_{DM} , in an application. Therefore the application's ambient temperature, T_A ($^{\circ}\text{C}$), and thermal resistance $R_{\theta JA}$ ($^{\circ}\text{C/W}$) must be reviewed to ensure that T_{JM} is never exceeded. Equation 1 mathematically represents the relationship and serves as the basis for establishing the rating of the part.

$$P_{DM} = \frac{(T_{JM} - T_A)}{R_{\theta JA}} \quad (\text{EQ. 1})$$

In using surface mount devices such as the SO8 package, the environment in which it is applied will have a significant influence on the part's current and maximum power dissipation ratings. Precise determination of P_{DM} is complex and influenced by many factors:

1. Mounting pad area onto which the device is attached and whether there is copper on one side or both sides of the board.
2. The number of copper layers and the thickness of the board.
3. The use of external heat sinks.
4. The use of thermal vias.
5. Air flow and board orientation.
6. For non steady state applications, the pulse width, the duty cycle and the transient thermal response of the part, the board and the environment they are in.

Fairchild provides thermal information to assist the designer's preliminary application evaluation. Figure 25 defines the $R_{\theta JA}$ for the device as a function of the top copper (component side) area. This is for a horizontally positioned FR-4 board with 1oz copper after 1000 seconds of steady state power with no air flow. This graph provides the necessary information for calculation of the steady state junction temperature or power dissipation. Pulse applications can be evaluated using the Fairchild device Spice thermal model or manually utilizing the normalized

maximum transient thermal impedance curve.

Thermal resistances corresponding to other copper areas can be obtained from Figure 25 or by calculation using Equation 2. The area, in square inches is the top copper area including the gate and source pads.

$$R_{\theta JA} = 79.9 + \frac{15}{0.14 + \text{Area}} \quad (\text{EQ. 2})$$

The transient thermal impedance ($Z_{\theta JA}$) is also effected by varied top copper board area. Figure 26 shows the effect of copper pad area on single pulse transient thermal impedance. Each trace represents a copper pad area in square inches corresponding to the descending list in the graph. Spice and SABER thermal models are provided for each of the listed pad areas.

Copper pad area has no perceivable effect on transient thermal impedance for pulse widths less than 100ms. For pulse widths less than 100ms the transient thermal impedance is determined by the die and package. Therefore, CHERM1 through CHERM5 and RHERM1 through RHERM5 remain constant for each of the thermal models. A listing of the model component values is available in Table 1.

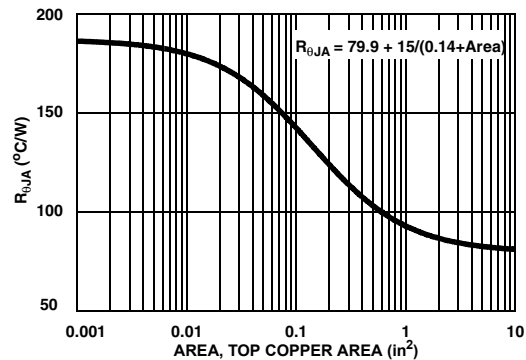


Figure 25. Thermal Resistance vs Mounting Pad Area

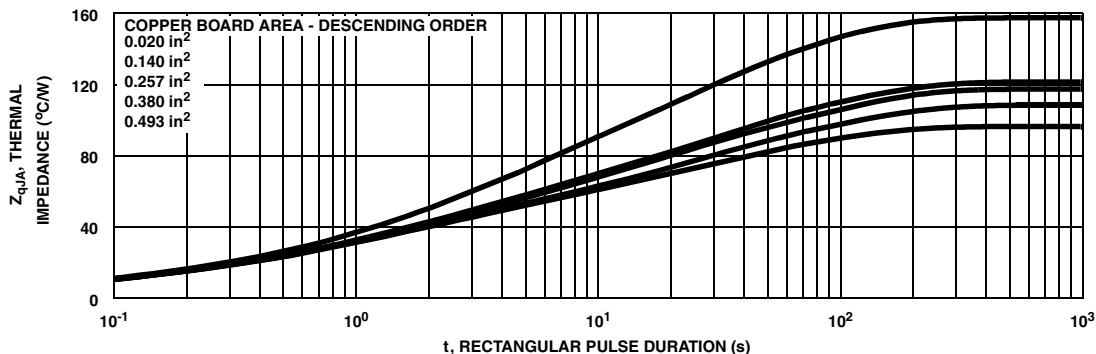


Figure 26. Thermal Impedance vs Mounting Pad Area

PSPICE Electrical Model

.SUBCKT FDSS2407 2 1 3 101 102 ; rev July 2004

Ca 12 8 1e-10

Cb 15 14 4e-10

Cin 6 8 2.8e-10

Dbody 7 5 DbodyMOD

Dbreak 5 11 DbreakMOD

Dplcap 10 5 DplcapMOD

CGATE 9 20 5e-9

DDISABLE 20 101 DDISABLEMOD

DFBK1 104 103 DFBK1MOD

DFBK2 7 104 DFBK2MOD

DFBK3 104 102 DFBK3MOD

RFBK1 5 103 RFBK1MOD 13e3

RFBK2 104 7 RFBK2MOD 2.15e3

Ebreak 11 7 17 18 67.4

Eds 14 8 5 8 1

Egs 13 8 6 8 1

Esg 6 10 6 8 1

Evthres 6 21 19 8 1

Evtemp 20 6 18 22 1

It 8 17 1

Lgate 1 9 1.8e-9

Ldrain 2 5 1.0e-9

Lsource 3 7 0.6e-9

RLgate 1 9 18

RLdrain 2 5 10

RLsource 3 7 6

Mmed 16 6 8 8 MmedMOD

Mstro 16 6 8 8 MstroMOD

Mweak 16 21 8 8 MweakMOD

Rbreak 17 18 RbreakMOD 1

Rdrain 50 16 RdrainMOD 3.5e-2

Rgate 9 20 RgateMOD 8.63e3

RSLC1 5 51 RSLCMOD 1e-6

RSLC2 5 50 1e3

Rsource 8 7 RsourceMOD 5.3e-2

Rvthres 22 8 RvthresMOD 1

Rvtemp 18 19 RvtempMOD 1

S1a 6 12 13 8 S1AMOD

S1b 13 12 13 8 S1BMOD

S2a 6 15 14 13 S2AMOD

S2b 13 15 14 13 S2BMOD

Vbat 22 19 DC 1

ESLC 51 50 VALUE={{(V(5,51)/ABS(V(5,51)))*(PWR(V(5,51)/(1e-6*20),3.5))}}

.MODEL DbodyMOD D (IS=1.1E-12 N=1.05 IKF=4e-1 RS=4.2e-2 TRS1=3e-4 TRS2=1.3e-6
+ CJO=3.3e-10 TT=3e-8 M=0.38, XTI=3.5)

.MODEL DbreakMOD D (RS=1 TRS1=1e-3 TRS2=-9e-6)

.MODEL DplcapMOD D (CJO=1.97e-10 IS=1e-30 N=10 M=0.84)

.MODEL DDISABLEMOD D (RS=30 IS=1e-15 BV=4.7 TBV1=-3e-4 TBV2=-3e-6 XTI=0)

.MODEL DFBK1MOD D (IS=1e-15 BV=23.8 IKF=2 TBV1=-6e-4 TBV2=6e-6)

.MODEL DFBK2MOD D (RS=1 IS=1e-30 BV=5.6 N=3.3 NBV=1)

.MODEL DFBK3MOD D (RS=1 IS=1e-15 BV=4.2 NBV=2.5)

.MODEL MmedMOD NMOS (VTO=1.7 KP=1.08 IS=1e-30 N=10 TOX=1 L=1u W=1u RG= 8.56e3)

.MODEL MstroMOD NMOS (VTO=2 KP=14 IS=1e-30 N=10 TOX=1 L=1u W=1u)

.MODEL MweakMOD NMOS (VTO=1.5 kp=0.04 IS=1e-30 N=10 TOX=1 L=1u W=1u RG= 8.56e4 RS=0.1)

.MODEL RbreakMOD RES (TC1=1.05e-3 TC2=-9e-7)

.MODEL RdrainMOD RES (TC1=9e-3 TC2=2.7e-5)

.MODEL RSLCMOD RES (TC1=2e-3 TC2=6e-6)

.MODEL RsourceMOD RES (TC1=3e-3 TC2=1e-6)

.MODEL RvthresMOD RES (TC1=-1.1e-3 TC2=-3.3e-6)

.MODEL RvtempMOD RES (TC1=-1.6e-3 TC2=1e-7)

.MODEL RFBK1MOD RES (TC1=-1.4e-3 TC2=1e-6)

.MODEL RFBK2MOD RES (TC1=-1.4e-3 TC2=1e-6)

.MODEL RgateMOD RES (TC1=-1.4e-3 TC2=1e-5)

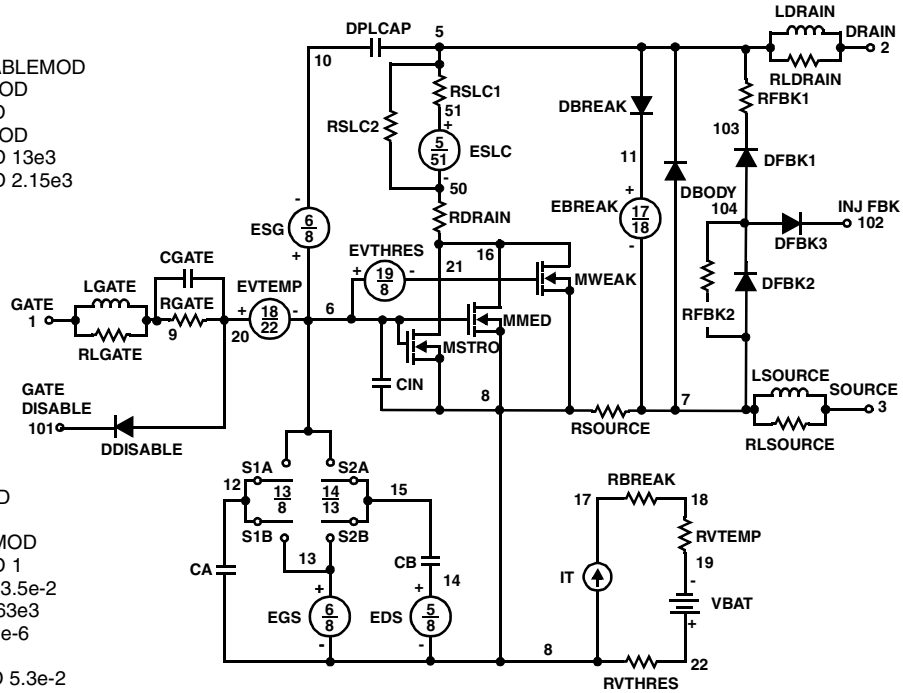
.MODEL S1AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-4.0 VOFF=-3.0)

.MODEL S1BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-3.0 VOFF=-4.0)

.MODEL S2AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-1.0 VOFF=-0.5)

.MODEL S2BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-0.5 VOFF=-1.0)

.ENDS



Note: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.

SPICE Thermal Model

REV July 2004
FDSS2407T
Copper Area = 0.5 in²

CTHERM1 Junction c2 1.2e-4
CTHERM2 c2 c3 2e-3
CTHERM3 c3 c4 2e-2
CTHERM4 c4 c5 3.0e-2
CTHERM5 c5 c6 4e-2
CTHERM6 c6 c7 7e-2
CTHERM7 c7 c8 2e-1
CTHERM8 c8 Ambient 2.8

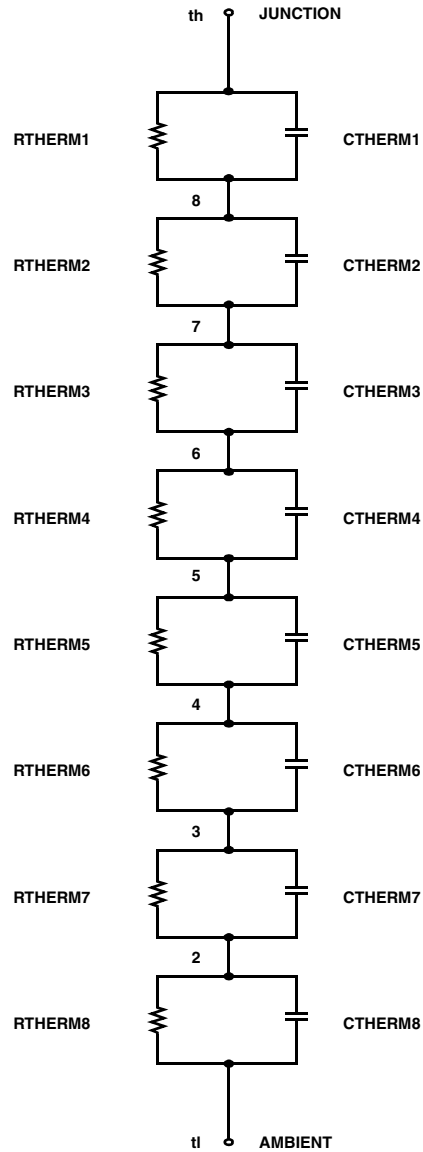
RTHERM1 Junction c2 1.4
RTHERM2 c2 c3 2.0
RTHERM3 c3 c4 2.8
RTHERM4 c4 c5 9.0
RTHERM5 c5 c6 18.0
RTHERM6 c6 c7 26.0
RTHERM7 c7 c8 28.0
RTHERM8 c8 Ambient 29.0

SABER Thermal Model

Copper Area = 0.5 in²
template thermal_model th tl
thermal_c th, tl

```
{
  ctherm.ctherm1 th c2 =1.2e-4
  ctherm.ctherm2 c2 c3 =2e-3
  ctherm.ctherm3 c3 c4 =2e-2
  ctherm.ctherm4 c4 c5 =3.0e-2
  ctherm.ctherm5 c5 c6 =4e-2
  ctherm.ctherm6 c6 c7 =7e-2
  ctherm.ctherm7 c7 c8 =2e-1
  ctherm.ctherm8 c8 tl =2.8
}
```

```
rtherm.rtherm1 th c2 =1.4
rtherm.rtherm2 c2 c3 =2.0
rtherm.rtherm3 c3 c4 =2.8
rtherm.rtherm4 c4 c5 =9.0
rtherm.rtherm5 c5 c6 =18.0
rtherm.rtherm6 c6 c7 =26.0
rtherm.rtherm7 c7 c8 =28.0
rtherm.rtherm8 c8 tl =29.0
}
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TRADEMARKS

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Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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Rev. I15



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- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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